Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	410	(451/63).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/22 13:57
L2	180	l1 and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/22 14:00
L3	35	non-contact adj polish$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/22 14:11
L4	53	non-contact adj2 polish$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/22 14:35
L5	231	(edge$1 with polish$3 with (semiconductor or wafer)).clm. and (abrasive or particles or slurry)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/22 14:14
L6	65	(edge$1 with polish$3 with (semiconductor or wafer)) and (abrasive or particles or slurry)	JPO	OR	OFF	2005/02/22 14:14
L13	2	"06023663"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/22 14:43
L14	4	("4323422").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/22 14:43
L15	732	(438/691).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/22 14:57
L16	2075	(438/692).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/22 14:57

L17	301	(451/44).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/22 14:59
L18	5	I17 and non-contact	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/22 14:59
L19	328	(156/345.12).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/22 15:05
L20	109	(156/345.13).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/22 15:06
L21	43	(156/345.17).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/22 15:06
L22	150	(156/345.18).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/22 15:06
L23	151	(156/345.23).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/22 15:06
L24	324	(451/66).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/22 15:06
L25	67	(451/106).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/22 15:06
L26	87	(451/93).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/22 15:07

L27	839	(134/1.3).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/22 15:07
L28	330	(134/135).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/22 15:07
L29	2278	(134/902).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/22 15:08
L30	4360	(l19 or l20 or l21 or l22 or l23 or l24 or l25 or l26 or l27 or l28 or l29)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/22 15:09
L31	94	l30 and non-contact	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/22 15:12
L32	11	l30 and contactless	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/22 15:10
L33	1496	l30 and edge$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/22 15:13
L34	1237	l30 and edge$1 and (wafer or semiconductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/22 15:13
S1	924	(451/36).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/22 13:57
S2	299	(451/44).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/22 15:04

S3	261	(451/40).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/22 16:11
S4	464	(S1 or S2 or S3) and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/22 16:12
S5	8	("2735232" | "4821466" | "5076026" | "5185957" | "5611725" | "5931718" | "5957753").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/01/22 16:16